

2018 Innovation and Technology Support Programme open for applications

The Innovation and Technology Commission is now inviting funding applications under the Innovation and Technology Support Programme (ITSP) of the Innovation and Technology Fund (ITF).

The ITSP adopts a three-tier funding framework. This application exercise covers Tier 2 and Tier 3 funding. Tier 2 involves the funding of applied research and development projects that are industry-oriented and have potential for commercialisation, while Tier 3 involves the funding of exploratory and forward-looking projects.

The application period commenced today (July 27) and will last until September 28 this year.

Further information and application procedures on the ITSP funding schemes are available on the ITF website (www.itf.gov.hk) and can be obtained from the ITF Secretariat at 21/F, West Wing, Central Government Offices, 2 Tim Mei Avenue, Tamar, Hong Kong (tel: 3655 5678; fax: 2957 8726; email: enquiry@itf.gov.hk).